

Financial Results for the Fiscal Year Ended March 31, 2024

May 2024
HIRATA Corporation
(6258)

Note: This document has been translated from the Japanese original for reference purposes only. In the event of any discrepancy between this translated document and the Japanese original, the original shall prevail.

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※ FY2023 : April 1, 2023 to March 31, 2024 FY2024 : April 1, 2024 to March 31, 2025





Company Name	HIRATA Corporation			
Headquarters	111 Hitotsugi, Ueki, Kita, Kumamoto, 861-0198 Japan			
Representatives	Yuichiro Hirata, President			
Date Established	Dec. 29, 1951			
Capital	2,633 million yen			
Our business	Manufacture and sales of various manufacturing line systems, Industrial robot and logistic equipment			
Stock Exchange Listings	Tokyo Stock Exchange, Prime Market (Code:6258)			
Employees	Consolidated 2,323 Non-Consolidated 1,419 **As of March 31, 2024			
Plants and office	7 bases in Japan (4 bases in Kumamoto 1 each in Tochigi, Shiga, Tokyo)			
Subsidiaries	3 subsidiaries in Japan (2 in Kumamoto, 1 in Tokyo) 9 overseas subsidiaries (America, Mexico, Germany, Singapore, Thailand, Malaysia, 2 in China·Taiwan)			







Consolidated Results

- Orders received: Orders received decreased from the previous period. Although we have been seen an increase in orders for automobile-related projects, such as EV and internal combustion engine systems, we have experienced a decrease in orders due to reduced investment in semiconductor-related equipment and a decline in orders for other automatic labor-saving equipment, such as logistics-related equipment and organic EL.
- Sales: Sales increased from the previous period. Despite the decrease in semiconductor-related and other automatic labor-saving equipment, we achieved an increase in revenue due to the contribution of increased sales in EV-related projects, particularly in the areas of EDUs and batteries.
- Operating profit: Operating profit increased from the previous period. The reason is due to the increase in sales of EV-related products and the improvement in the cost ratio of semiconductor-related products.

	EV2022	EV2022	YoY C	hange
	FY2022	FY2023	Amount of +/-	Percentage of +/-
Orders Received	93,758	86,239	△7,519	△8.0%
Sales	78,443	82,839	4,395	5.6%
Operating Profit (profit ratio)	5,920 (7.5%)	6,047 (7.3%)	127	2.2%
Ordinary Profit	5,802	6,259	456	7.9%
Profit attributable to owners of parent	4,269	4,344	74	1.7%
Backlog of Orders	62,004	65,404	3,399	5.5%

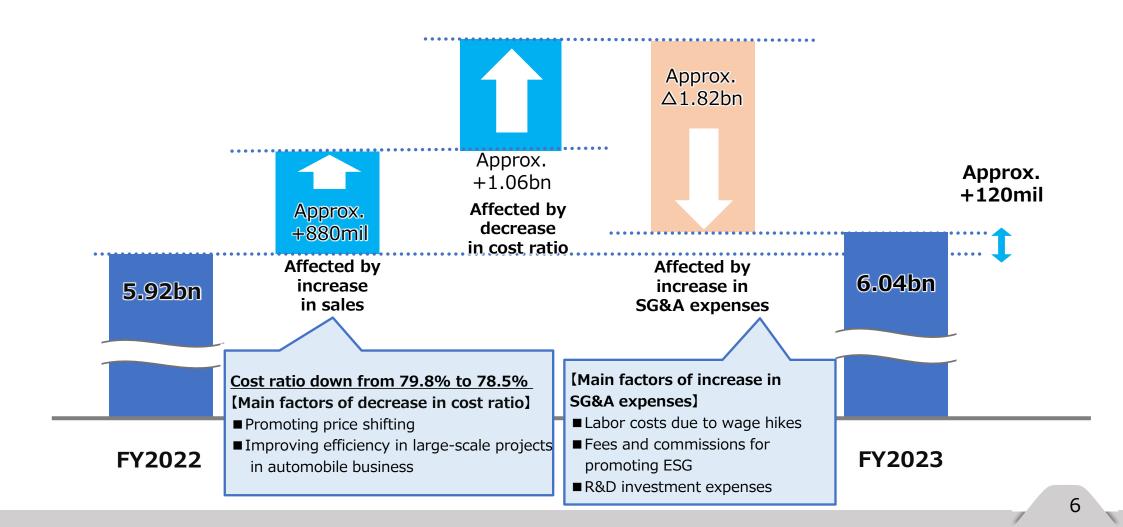


Factor Analysis on Changing Operating Profit

■ Operating profit increased approximately 120 million yen from the same period of the previous year.

[Main factors for increase] The increase in sales and the improvement of cost ratio by promoting price shifting, etc.

[Main factors for decrease] The increase in SG&A expenses due to the implementation of growth investments, such as wage increases, ESG promotion expenses, and research and development investments.



Hirata The Global Production Engineering Company

I. FY2023 Full Year Results (Consolidated)

Sales, Received Orders, and Backlog of Orders by Business Segment

				YoY C	hange
	Business Segment	FY2022	FY2023	Amount of +/-	Percentage of +/-
	Automobile	38,165	44,492	6,327	16.6%
	Semiconductor	34,047	25,107	△8,940	△26.3%
Received orders	Other Automatic Labor-saving Equipment	19,123	14,357	△4,765	△24.9%
0.0.0	Others	2,422	2,281	△140	△5.8%
	Total	93,758	86,239	△7,519	△8.0%
	Automobile	30,298	36,984	6,686	22.1%
	Semiconductor	28,954	27,390	△1,564	△5.4%
Sales	Other Automatic Labor-saving Equipment	16,952	16,083	△869	△5.1%
	Others	2,238	2,381	143	6.4%
	Total	78,443	82,839	4,395	5.6%
	Automobile	31,642	39,150	7,507	23.7%
	Semiconductor	21,753	19,470	△2,282	△10.5%
Backlog of Orders	Other Automatic Labor-saving Equipment	8,021	6,295	△1,725	△21.5%
	Others	588	488	△99	△16.9%
	Total	62,004	65,404	3,399	5.5%

Details of Received Orders and Sales by Business Segment

■ Automobile -related

Received orders increased from the same period of the previous year. Both EV and internal combustion engine projects have been in high demand, and we have also secured large-scale contracts for internal combustion engines.

Sales increased from the same period of the previous year. The already contracted EV-related projects (mainly EDU and battery-related), contributed the sales this year.

■ Semiconductor -related

Received orders decreased from the same period of the previous year. The received orders related to wafer transportation increased, but other areas such as inspection equipment and PLP decreased, which had an impact.

Sales decreased from the same period of the previous year. Sales were also affected by the decrease in areas other than wafer transportation, similar to the received orders.

			FY2	022	FY2023		YoY Cl	nange
			Actual results	Segment composition	Actual results	Segment composition	Amount of +/-	Percentage of +/-
	Automobile-	EV	30,239	79.2%	25,112	56.4%	△5,127	△17.0%
	related	Others	7,926	20.8%	19,380	43.6%	11,454	144.5%
Received	Semiconduc	Wafer transfer	19,731	58.0%	16,646	66.3%	△3,084	△15.6%
orders	tor-related	Others	14,316	42.0%	8,460	33.7%	△5,855	△40.9%
	Other Automatic	Organic EL	4,739	24.8%	4,451	31.0%	△287	△6.1%
	Labor-saving Equipment	Others	14,383	75.2%	9,905	69.0%	△4,477	△31.1%
	Automobile-	EV	19,723	65.1%	27,627	74.7%	7,903	40.1%
	related	Others	10,575	34.9%	9,357	25.3%	△1,217	△11.5%
Calos	Semiconduc	Wafer transfer	15,398	53.2%	18,836	68.8%	3,438	22.3%
Sales	tor-related	Others	13,556	46.8%	8,553	31.2%	△5,002	△36.9%
	Other Automatic	Organic EL	5,529	32.6%	4,157	25.8%	△1,372	△24.8%
	Labor-saving Equipment	Others	11,422	67.4%	11,925	74.2%	503	4.4%



Operating Profit (ratio) by Business Segment

■ **Automobile** Operating profit improved from the same period of the previous year.

-related Despite surpassing the previous year due to progress in cost transfer.

Despite surpassing the previous year due to progress in cost transfer and improvement in cost rate through increased proficiency, The operating profit margin was lower than the previous year due to an increase in the ratio of SG&A expenses borne by the

segment as a result of the large increase in sales.

■ Semiconductor -related

Operating profit improved from the same period of the previous year. Despite a decrease in revenue, we were able to achieve an increase in profit through improvements in cost rates due to progress in cost transfer and other factors. Additionally, the relatively high-profit margin wafer transportation-related segment increased its composition ratio, resulting in an operating profit margin exceeding the previous year.

■ Other Automatic Labor-saving Equipment Operating profit decreased from the same period of the previous year due to a decrease in sales in the high-profit margin organic EL-related segment.

	Automobile-related			related La		Other Automatic Labor-saving Ot Equipment		Others		idation nation	Total	
	FY2022	FY2023	FY2022	FY2023	FY2022	FY2023	FY2022	FY2023	FY2022	FY2023	FY2022	FY2023
Sales	30,298	36,984	28,954	27,390	16,952	16,083	2,238	2,381	△0	△ 0	78,443	82,839
Operating profit	1,559	1,651	3,445	4,450	930	119	△19	△177	4	4	5,920	6,047
Operating profit ratio	5.1%	4.5%	11.9%	16.2%	5.5%	0.7%	△0.9%	△7.5%	-	_	7.5%	7.3%

Hirata The Global Production Engineering Company

I. FY2023 Full Year Results (Consolidated)

Balance Sheet·Key Management Indicators

Assets	FY2022	FY2023	YoY Change
Current Assets	79,655	88,554	8,898
Cash and deposits	11,134	10,652	△481
Trade receivables, etc.	51,435	59,504	8,068
Inventories	14,219	14,264	45
Others	2,865	4,131	1,266
Tangible Assets	34,867	42,233	7,366
Tangible fixed assets	24,302	27,437	3,135
Intangible fixed assets	749	904	155
Investment and other assets	9,815	13,891	4,075
Total Assets	114,522	130,787	16,265

Liabilities	FY2022	FY2023	YoY Change
Current Liabilities	43,193	49,864	6,671
Fixed Liabilities	11,754	15,621	3,867
Total Liabilities	54,947	65,485	10,538
Net Assets			
Total Net Assets	59,575	65,302	5,726
Key Management Indicators			
PBR	1.20(x)	1.25(x)	0.05
ROE	7.5%	7.0%	△0.5pt
Equity Ratio	51.7%	49.7%	△2.0pt

II. FY2024 Full Year Forecasts (Consolidated)





II. FY2024 Full Year Forecasts (Consolidated) Hirata The Global Production Engineering Company

Full Year Forecast

■ Projected increase in revenue of 100 billion yen and operating profit of 7.5 billion yen.

		FY20	23	FY20)24	vs. FY2023	
	results		Full year t	Full year forecast		Percentage of +/-	
	Sales	82,839	_	100,000	_	17,160	20.7%
	Automobile-related	36,984	-	50,000	I	13,015	35.2%
	Semiconductor-related	27,390	_	29,000	I	1,609	5.9%
	Other Automatic Labor- saving Equipment	16,083	_	19,000	I	2,916	18.1%
	Others	2,381	-	2,000	1	△381	△16.0%
0	perating Profit (x)	6,047	(7.3%)	7,500	(7.5%)	1,452	24.0%
C	Ordinary Profit (x)	6,259	(7.6%)	7,300	(7.3%)	1,040	16.6%
	Profit attributable to owners of parent (x)	4,344	(5.2%)	4,700	(4.7%)	355	8.2%

II. FY2024 Full Year Forecasts (Consolidated) Hirata The Global Production Engli



Key points of the full year forecast

Sales

In addition to securing the highest level of order backlog at the beginning of the fiscal year 2024, we anticipated a continued robust order intake in the EV and semiconductor sectors, leading to a projected increase in revenue compared to the previous period.

(Units in millions of Yen)

	FY2023	FY2024	YoY Change	
	results	Full year forecast	Amount of +/-	Percentage of +/-
Sales	82,839	100,000	17,160	20.7%

<Outlook for each segment>

(Automobile-related)

- ·While we observe a slowdown in the growth of the EV market in North America, we will leverage our strength in being able to cater to EVs, internal combustion engines, and hybrids to capture demand effectively.
- •We expect an increase in orders by establishing a dedicated department for EV battery charging and discharging related equipment starting from FY 2024, and actively participating in our customers' product development stages.

(Semiconductor-related)

- ·We will ensure to capture the expanding demand through active investment in back-end process manufacturing equipment for generative AI and power semiconductors for automotive applications.
- •We will proceed with the establishment of a production collaboration system with local subsidiaries in Southeast Asia, in addition to existing ones in China and Taiwan in order to expand our production capacity.

(Other automatic labor-saving equipment)

•With the enlargement of organic EL panels, we will specialize in the production of the core components. Development of assembly equipment for a home electronics manufacturer is ongoing at the client, and we will work to recover from development delays.

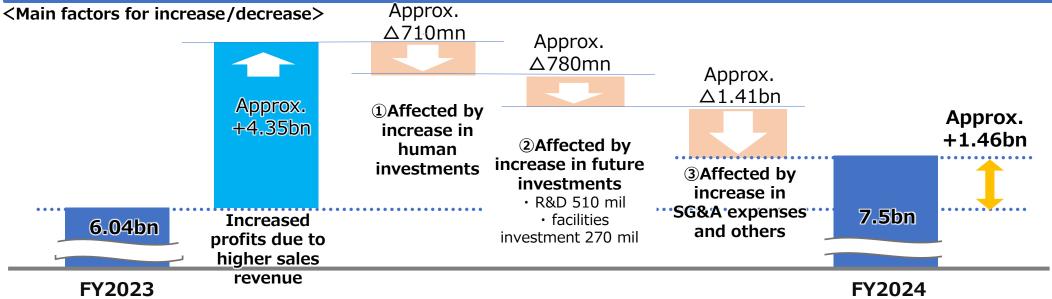
II. FY2024 Full Year Forecasts (Consolidated)



Key points of the full year forecast

Operating profit

We will actively implement investments in human resources and growth to achieve "profitability enhancement" and "strengthening of management foundation" for the next phase of growth. We anticipate an increase in operating profit compared to the previous period.



Factors affecting profit and loss Impact		Contents	
①Personnel investment		•Increase in hiring to meet future demand growth •Increase in personnel expenses to address the rapid increase in prices and ensure stable talent acquisition	
②R&D investment	780 million yen	 Accelerating the development of next-generation product in existing businesses Capital investment for improving productivity, etc. 	
3Other selling, general, and administrative expenses1.41 billion yen		 Increase in selling, general, and administrative expenses due to sales expansion Increase in procurement cost, etc. 	

Transition and Forecast of Dividends and Dividend Ratio per Share

(Units in Yen)

	FY2019	FY2020	FY2021	FY2022	FY2023	FY2024 forecast
Dividends per Share (yen)	40.00	65.00	65.00	90.00	100.00	120.00
Dividend Ratio (%)	23.8	16.6	25.2	21.9	23.9	26.5

Note: Dividend ratio is on a consolidated basis.

Our approach to dividends

We fully consider profit return to our shareholders as one of the highest priority issue. So, we endeavor to pay dividend stably and continually to be more than 20% of the consolidated dividend ratio as a guide by strengthening our financial characteristic and also taking our consolidated performance and business deployment into consideration.

Regarding this fiscal year's dividend, taking into account the above basic policy and the business environment surrounding our company, we have decided on 100 yen. Additionally, for the next dividend, we anticipate 120 yen as the year-end dividend.

Regarding our approach to future dividends, we are currently considering capital policies including shareholder return strategies. We will work to provide a clear direction within the next medium-management plan.

Ⅲ. Outlook for the Medium-Term Management Plan (FY2022-2024)





Ⅲ. Outlook for the Medium-Term Management Plan (FY2022-2024)



We forecast sales of 100 billion yen and an operating profit of 7.5 billion yen for the final year of the medium-term management plan.

Market Environment

Automobile

- The EV market is in an expanding trend.
- Equipment investment for engine cars and hybrid cars is also getting active.

Semiconductor

- After a period of inventory adjustment until last year, there is a recovering trend.
- Investment in automotive power semiconductors and AI for power generation is active.

Other
Automatic
Labor-saving
Equipment

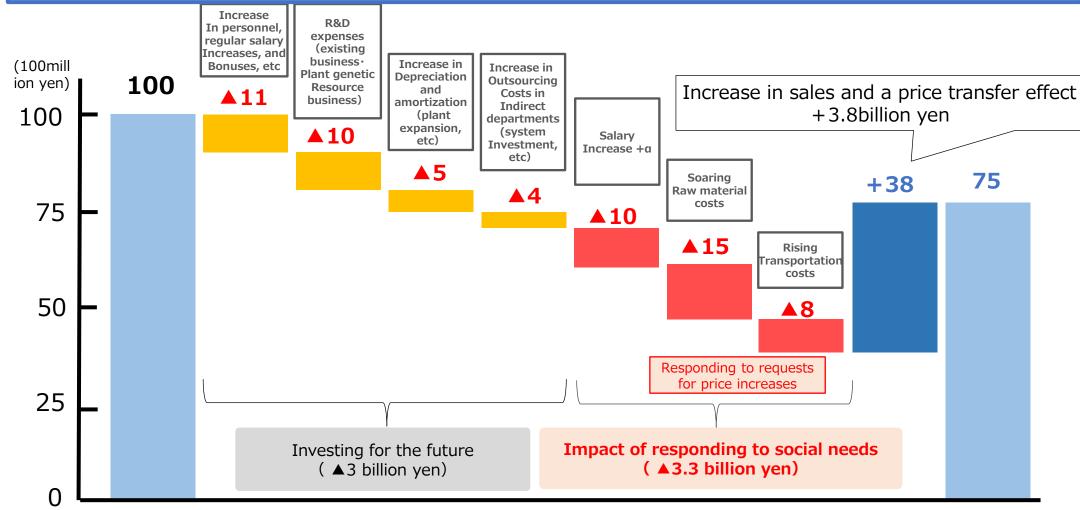
- With the enlargement of organic EL panels, the production of largesized processed products are transitioned to local manufacturing.
- Customer-driven new technology development is underway in the field of home appliances.

Ⅲ. Outlook for the Medium-Term Management Plan (FY2022-2024)



Difference in operating income forecast

Due to increased labor costs from wage hikes surpassing the inflation rate, as well as rising costs of raw materials and transportation expenses beyond the assumptions made during the medium-term plan formulation, we are forecasting an operating profit of 7.5 billion yen.



Targets at the time of medium-term management plan formulation (As of FY2021)

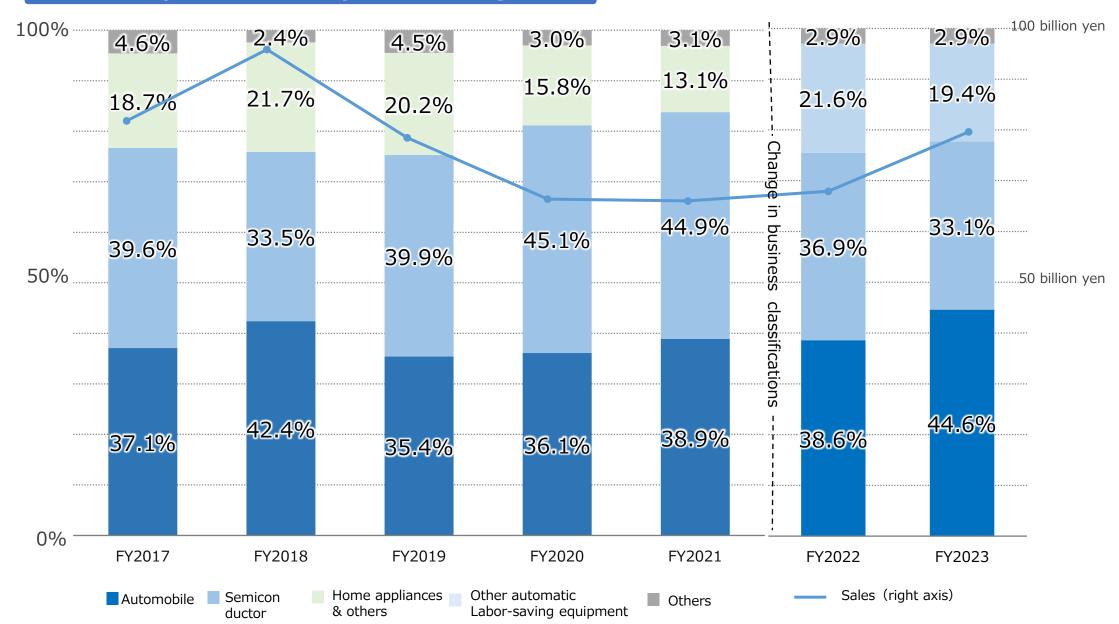
FY2024 Full year forecast







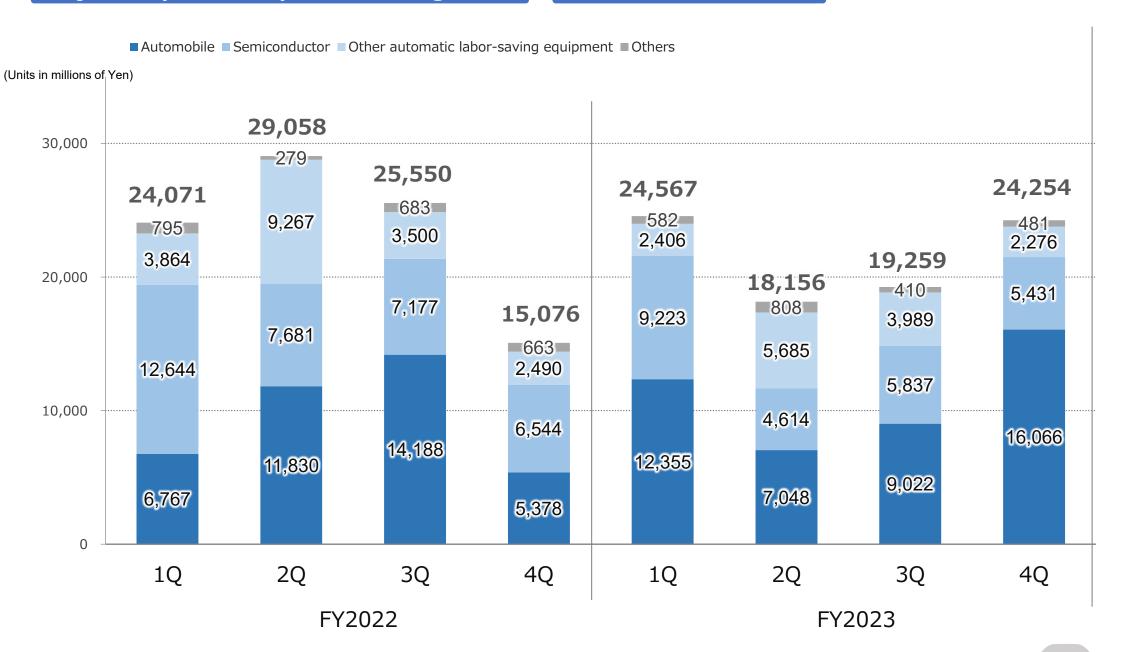
Sales Composition Ratio by Business Segment





Quarterly Trends by Business Segment

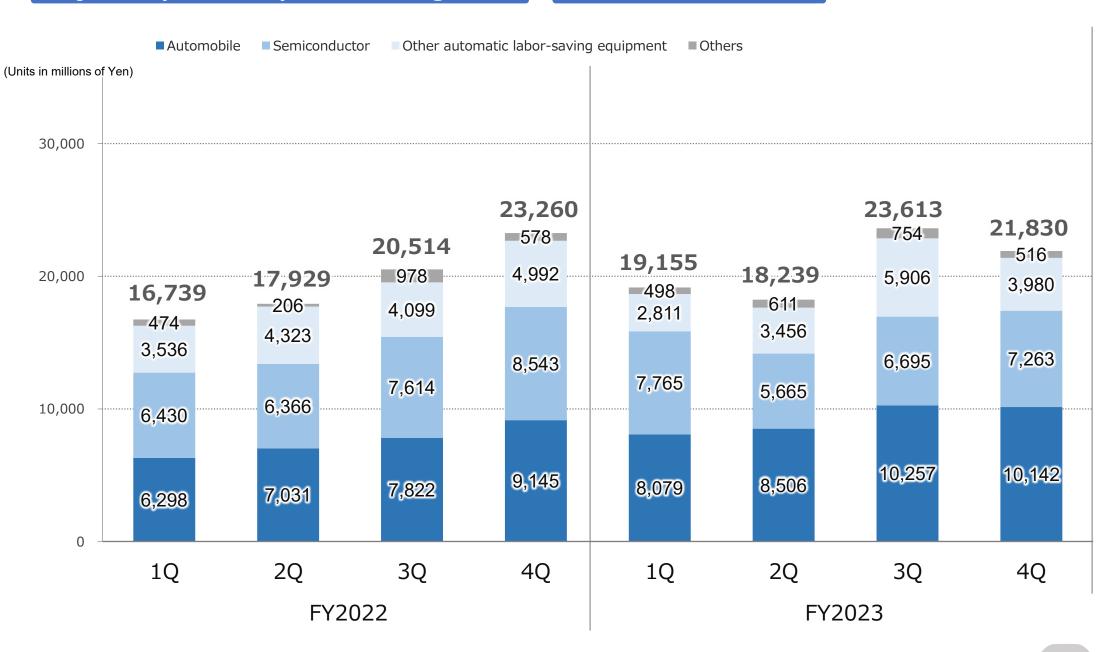
Received Orders





Quarterly Trends by Business Segment

Sales

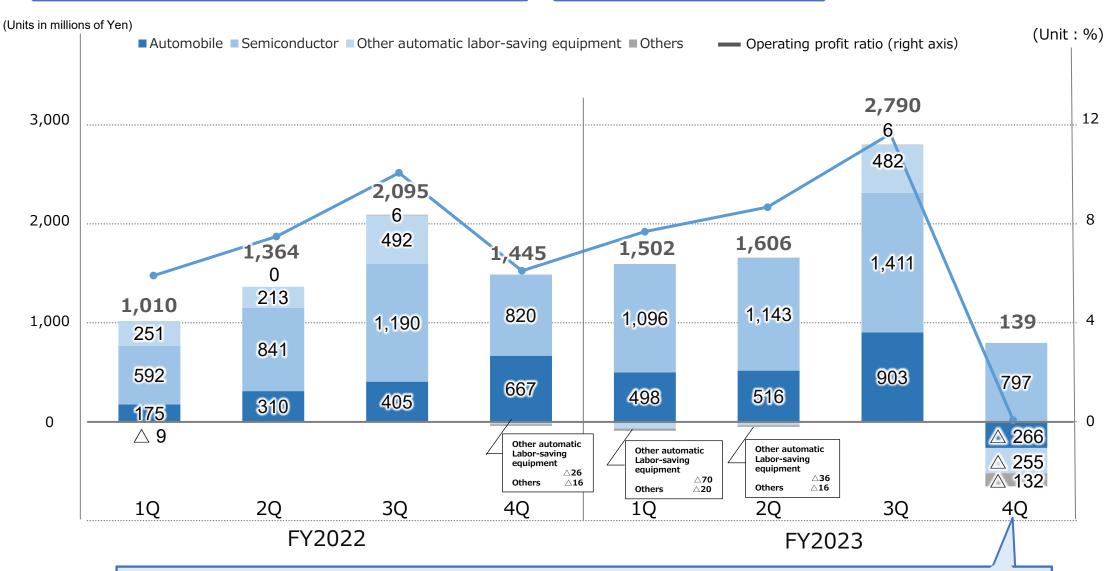




Quarterly Trends by Business Segment

Operating profit

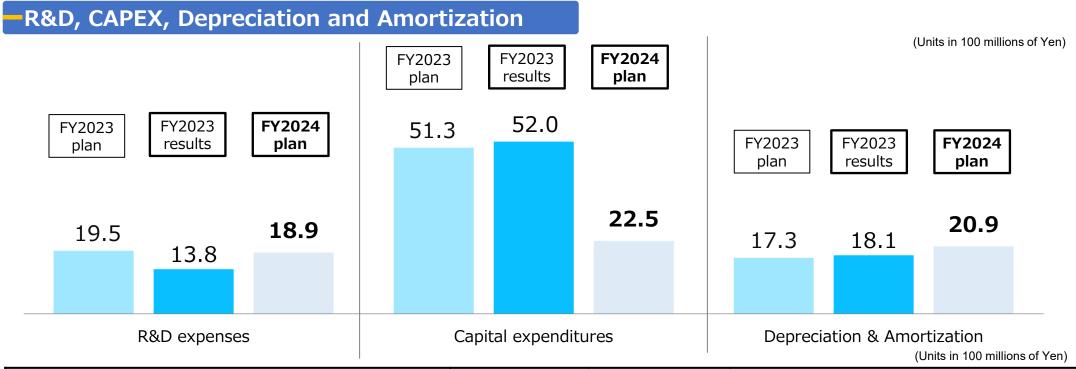
%Before segment elimination



[Cause of decrease in profit in the fourth quarter]

Profits decreased in all segments due to the increase in employee and executive bonuses based on performance and the specific expenses incurred at the end of the period.





Main investments		FY2023 results	FY2024 plan	Reasons for increase/decrease
R&D	Next generation product development in existing businesses	Approx. 9.2	Approx. 12.3	Promoting development of mass-produced products
expenses	Plant genetic resource related business	Approx. 4.5	Approx. 6.6	Increased in depreciation and personnel expenses
	Plant rebuilding and expansion	Approx. 22.6	Approx. 3.6	Large-scale rebuilding and expansion have temporarily halted until the previous period.
Capital	Plant genetic resource related business	Approx. 15.3	Approx. 0.1	The introduction of major equipment was completed by the previous period.
investment	Information system related	Approx. 2.1	Approx. 1.8	The implementation of the next-generation core system is still ongoing.
	Others	Approx. 12.2	Approx. 17.1	There is a gathering of small-scale investments, among other things, for the purpose of improving productivity.

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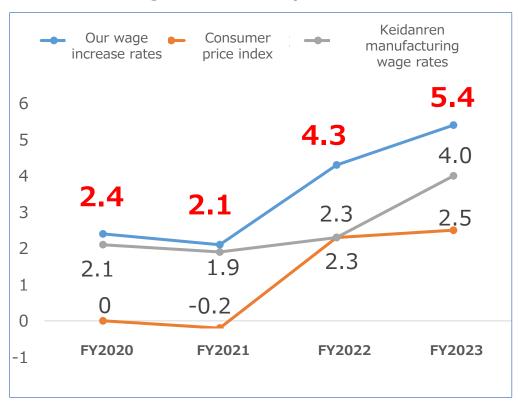


Plans for personnel investment

- We secure human resources continuously for the business expansion in the future.
- We work on talent retention through wage improvements, work style reforms, enhancement of employee benefits, and the provision of education and training.
- **■** Status of human resources recruitment

Career recruitment 78 persons Number of applicants More than 2,500 persons *Employees who joined the company in April 2024

■ Trends in wage increase implementation rates





Responses to the Assumed opportunities / risks of the major anticipated external environment

Assumed major external environment	Assumed opportunities / risks	Major countermeasures	
Strengthening countries' efforts to decarbonize and become carbon neutral	[Opportunity] Increase in demand related to EV and semiconductor related business [Risk] ·Actions taken to reduce GHG emissions (cost increase) ·Missed orders due to lack of production capacity and human resources	 Improvement of QCD to obtain continuous inquiries from existing customers Positioning EVs and semiconductors as growth areas and concentrating resources Upfront investment in human resources and production capacity in anticipation of increased orders (Increase in personnel, Kansai plant reconstruction, Shichijo plant expansion, etc.) Establishment of GHG emission reduction targets and study of optimal target achievement measures 	
Slowdown in environmental-related investments due to change of government in North America	【Risk】 ·Decreased capital investment by customers due to EV market contraction	 Understand capital investment trends through close information exchange with customers Securing new customers and projects by expanding the areas of service Diversify core businesses and optimize resource allocation 	
Mass-production of new type batteries	[Opportunity] Expanding business opportunities through the pursuit of new technologies and the ability to mass-produce [Risk] Deterioration in profitability due to the burden of development factors	 Participating from the research and development stage of our customers and developing and proposing that meet their requirements Reducing R&D expenses through external sourcing/procurement 	
Proliferation of generative AI [Opportunity] Increase in demand related to semiconductor related business [Risk] Missing orders due to lack of production capacity and human resources		 Improvement of QCD to obtain continuous inquiries from existing customers Resource investment in semiconductor field Upfront investment in human resources and production capacity in anticipation of increased orders 	
Concentration of semiconductor-related industries in Kumamoto and Kyushu [Opportunity] Increase in demand related to semiconductor related business [Risk] Shortage of human resources due to competition of talent acquisition		 Improvement of QCD to obtain continuous inquiries from existing customers Resource investment in semiconductor field Upfront investment in human resources and production capacity in anticipation of increased orders Recruiting new talent actively Implementing wage revisions and retention measures taking into account societal trends. 	



Responses to the Assumed opportunities / risks of the major anticipated external environment

Assumed major external environment	Assumed opportunities / risks	Major countermeasures	
Escalation of tensions in the Middle East	【Risk】Soaring of crude oil prices, cost increases in transportation and procurement	 Incorporating estimates for increased transportation costs and procurement costs, as well as implementing price revisions Developing new suppliers Reduction in the number of required parts and materials through standardization 	
Increase in personnel expenses based on social demands	(Risk) · Deterioration in profit marginDecrease in competitiveness due to sales price increase	●Incorporating estimates for increased labor costs and implementing price adjustments to pass on the costs ●Establishing competitive advantages other than price	
Soaring and stagnating raw materials and component prices	【Risk】·Deterioration in profit margin ·Decrease in competitiveness due to sales price increase	 Incorporating estimates for increased procurement costs and implementing price adjustments to pass on the costs Developing and launching high-value-added products Developing new suppliers Reduction in the number of required parts and materials through standardization 	
Shortage of parts and materials	【Risk】 Decreased sales, deterioration in cost ratio, and increased inventory assets due to production schedule delays and prolonged lead times	 Securing parts inventory by making advance arrangements Developing new suppliers Reduction in the number of required parts and materials through standardization 	
The logistics "2024 problem"	 (Risk) ·Increased procurement costs due to rising transportation fees ·Prolonged lead times for procurement and shipment 	 ● Incorporating estimates for increased procurement costs and implementing price adjustments to pass on the costs ● Reduction in the number of required parts and materials through standardization ● Logistics arrangements anticipating prolonged lead times 	
Exchange rate (Progress in the depreciation of the yen)	 (Opportunity) Increased relative price competitiveness with overseas competitors (Risk) ·Substantial increase in the actual procurement prices of overseas sourced materials and components 	 Actively expanding the acquisition of overseas projects Reduction in the number of required parts and materials through standardization 	



Topics: Receiving large-scale purchase orders

■ The list of large-scale purchase order projects we disclosed starting from FY2023 and onwards

Business segment	Disclosure date		Outline of the equipment	Amount
	2023	June	EDU assembly equipment for EVs	More than 8 billion yen
Automobile- related	2024	January	Battery charging and discharging related equipment for EVs \times	More than 4 billion yen
		February	Engine assembly equipment for internal combustion engines	Approximately 13 billion yen

<Orders record of battery charging and discharging related equipment for EVs>

The cumulative order amount since the fiscal year 2022 has exceeded 6.5 billion yen. (5 lines)

- ① Before Dec. 2023 The order amount is approx. 2.5 billion yen. (2 lines)
- ② In Jan. 2024 The order amount is more than 4 billion yen. (3 lines) (above ※)
- We started full-scale orders for battery charging and discharging related equipment from the fiscal year 2022.
- Our ability to handle large-scale projects and our track record of delivering battery charging and discharging related equipment for EVs has been recognized, leading to the acquisition of new orders.



Strengthening our efforts in ESG management

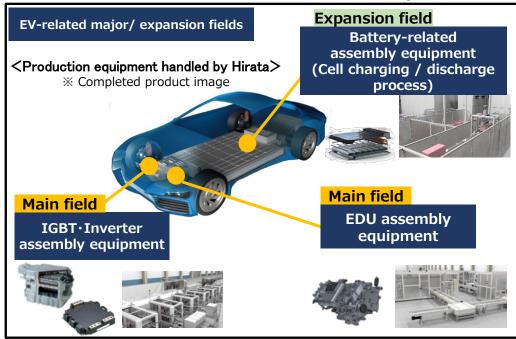
2022	Oct.	Human Rights Policy is formulated and Procurement Basic Policy is revised.				
2023	Apr.	The Sustainability Promotion Committee is established.				
		Sustainability page is established in our web page and the dissemination of ESG information is been strengthened.				
	Sep.	We signed the UN Global Compact.				
	Oct.	Human rights due diligence is implemented.				
	Nov.	We express our support for the Keidanren's "Corporate Code of Conduct."				
2024	Jan.	Code of Conduct of the Hirata Group is established.				
		Human Rights Respect Working Group within the Sustainability Promotion Committee is established.				
	Apr.	We obtained EcoVadis [Bronze] evaluation.				





Business overview : Main products of automobile-related business

√Continued orders from North American automakers (big three), North American emerging EV manufacturers, domestic electronic components manufacturers, focusing on EV related



Main field

EDU assembly equipment

Manufacturing EV-drive parts assembly equipment called EDU (ELECTRIC DRIVE UNIT) combined with in-vehicle motors and gearboxes

Main field

IGBT· Inverter assembly equipment

Manufacturing of in-vehicle electronic components mounted on EVs and transmissions such as IGBT and inverters

Expansion field

Battery-related assembly equipment(Cell charging / discharge process)

Manufacturing of conveying equipment for charging and discharging processes that are part of the battery cell progress.

Main Areas, customers, superiority

Major fields	Areas	Customers	Hirata's superiority	
EDU assembly equipment	North America	North American automakers (Big Three) North American emerging EV manufacturers	 Ability to handle large facilities, some of which exceed 1 km in total length, solely in-house A vast factory that allows us to build the customer's 	
IGBT· Inverter assembly equipment	Japan	Domestic electronic components manufacturers	production line in our factory and install it on site after verifying the production capacity and quality • Integrated system from development to production	
Battery-related assembly equipment(charging / discharge process)	Japan	Domestic battery manufacturers	and maintenance • Engineering ability to respond to customer request	

IV. Reference Data (13)

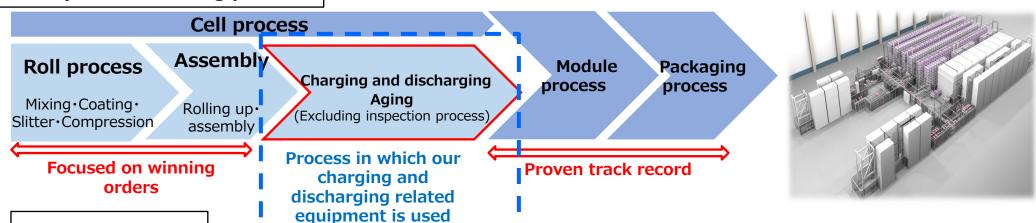


Business overview: Charging and discharging related equipment

- We have charge and discharge equipment that handles the final process of cell manufacturing, which is the "charging and discharging" process.
- We have a competitive advantage in systematization utilizing conveyance and stocking technologies.

Battery manufacturing process

• Image of charging and discharging facilities



Our products

Charging and discharging related equipment

- The process of activating cells (batteries) by applying power to the assembled cells and repeating charging and discharging in the initial stage, after aging, after high temperature testing, etc.
- We deliver the system to the customer by incorporating the charging and discharging machines procured from external suppliers into the transport lines and automated warehouses manufactured by us.

<Transport system>

This system provides optimal transfer between processes according to recipes (process procedures).

<Warehouse system for aging>

The system performs tests in high-temperature environments and measures the performance of cell voltages after a certain period of time in an automated warehouse.

< Warehouse system for charging and discharging>

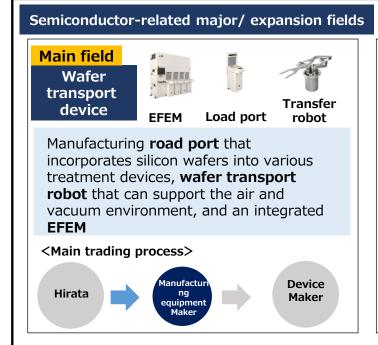
It is used in a process in which a full charge and discharge are repeated several times. It takes several hours to set the charging capacity, charging speed, and number of repetitions.

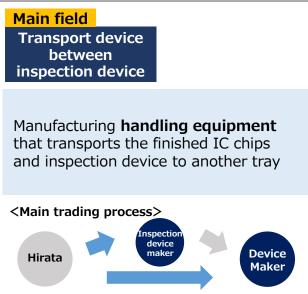
IV. Reference Data (4)

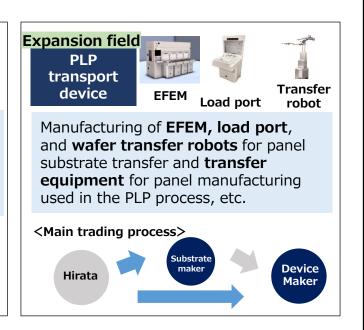


Business overview: Main products of semiconductor-related business

✓ Continuing orders mainly for wafer transport devices for domestic device manufacturers and handling devices between inspection devices







Main customers, competitors, superiority

Major fields	Areas	Customers	Hirata's superiority
Wafer transport device	Japan	Domestic manufacturing equipment manufacturer	• A was like of some mank line was
Transport device between inspection device	North America, Japan	North American device maker Domestic inspection equipment manufacturer	 A wealth of component lineup Knowledge technology required for customization and optimization to meet customer requirements Integrated system from development to production and
PLP transport device	North America, Europe, Japan	North American device maker Domestic/European substrate manufacturer	maintenance ■ Engineering ability to respond to customer requests



Business overview: Wafer transport device

• Manufacturing of load ports that take wafers into various processing equipment mainly used in the front-end process of semiconductor manufacturing, wafer transfer robots that transfer wafers, and EFEMs that integrate them

Semiconductor manufacturing process

Process in which our wafer transfer equipment is primarily used

Front-end process

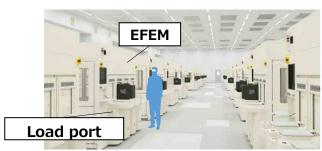
Design

Back-end process

- Design for circuit and pattern Photomask creation
- Wafer creation
- Circuit pattern creation
 - Oxidation of wafer surface
- •Thin film formation
- ·Pattern transcription of photomask
- Ion implantation

- Dicing
- Die bonding
- Wire bonding
- Packaging
- Commercialization and final inspection

Image of our product installation



Multiple EFEM/load ports are used on a single line because EFEM/load ports are installed at each processing unit.

> FFU (Fan Filter Unit)

Our main products

(1) **EFEM** (Equipment Front End Module)

It is placed for each processing unit, with a wafer transfer robot inside and a load port on the front.

2 Load port

It opens and closes the lid on the back side of the FOUP X, a device that makes up the EFEM, but is also sold as a standalone item.

3 Wafer transport robot

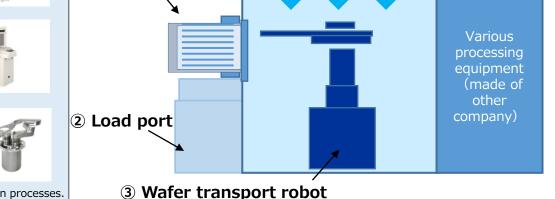
Wafers are removed from the FOUP and transferred to the processing equipment. After processing, the wafers are stocked back in the FOUP. It is a device that makes up the EFEM, but is also sold as a stand-alone item.



FOUP: It is a container for wafers that holds multiple wafers and moves them between processes.







Installation image of our products

FOUP (made of

other company)

1 EFEM



Business overview : PLP transport device

Designing and manufacturing conveyance equipment used in PLP, an advanced packaging technology that is expected to expand

Semiconductor manufacturing process

Process in which our PLP is primarily used

Design

Front-end process

Back-end process

Design for circuit and patternPhotomask

creation

- Wafer creationCircuit pattern creation
- $\boldsymbol{\cdot} \mathsf{Oxidation} \; \mathsf{of} \; \mathsf{wafer} \; \mathsf{surface}$
- Thin film formation
- •Pattern transcription of photomask
- Ion implantation

- Dicing
- Die bonding
- Wire bonding
- Packaging
- Commercialization and final inspection

What is PLP (Panel Level Packaging) about?

- The packaging process involves rearranging numerous chips that have been individually cut after circuit formation onto thin, square-shaped substrates and then collectively molding them. This is a packaging technology called "PLP".
- In PLP, panel substrates larger than the standard 300mm wafer size, such as 510x515mm square, are commonly used.
- The panel substrate uses printed circuit boards, glass substrates for LCD panel manufacturing, and copper plates.

Difference of packaging process

Conventional packaging

WLP

(Wafer Level Package)

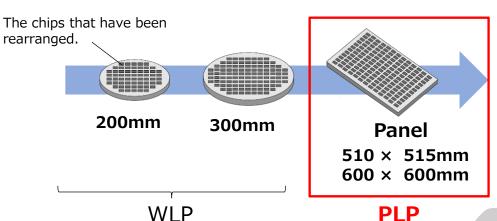
PLP

(Panel Level Package)

Circuits are formed on wafters, and after cutting the chips into smaller pieces, they are individually bonded and encapsulated onto substrates to complete the product.

After cutting the chips individually, only the good chips are rearranged on the wafer, and then they are bonded and encapsulated onto the substrate while the chips are still on the wafer. They are then cut individually.

After cutting the chips individually, only **the good chips are rearranged on a square-shaped panel,** and then they are bonded and encapsulated onto the substrate while the chips are still on the panel. They are then cut individually.





Business overview: Other Automatic Labor-saving Equipment

✓ Manufacturing products for various industrial fields such as organic EL vapor equipment, assembly equipment for home appliances, and medical physics and chemical equipment

その他自動省力機器の主力・新規分野

Main field

Organic EL Vapor equipment Contracted the manufacturing of vacuum vapor equipment for organic EL panels

Main field

Assembly equipment for home appliances

Manufacturing all equipment, including motor assembly equipment built into high-performance home appliances Main field

Medical

physiology

and chemical

equipment

Manufacturing a system for sample tests (pathological tissue specimen device and fully automatic continuous thinning device)

New field for monetization

Focused ultrasound therapy equipment

- •Focused ultrasound therapy equipment for Pancreatic Cancer Under Development with SONIRE Therapeutics Inc. (Headquarters: Shinjuku-ku, Tokyo, SONIRE, hereinafter, Sonia)
- •Aiming for non-invasive cancer treatment that fuses SONIRE's Ultrasonic Technology with our robot technology
- ·Started clinical trials in a person and started developing the next mass production device

Main customers, competitors, superiority

Major fields	Areas	Customers	Hirata's superiority
Organic EL Vapor equipment	Japan	Domestic manufacturing device manufacturer	 Extensive knowledge and expertise in production
Assembly equipment for home appliances	Asia	Asian home appliance manufacturer	facilities and equipment in various fields • Integrated system from development to production and
Medical·physics and chemical equipment	Japan	Domestic medical specialty manufacturer	maintenance ● Engineering ability to respond to customer requests



Forecasts and other forward-looking statements presented here represent judgment we made based on information available at the time this presentation was prepared, and involve risks or uncertainties, such as economic conditions, competition with rival companies, and exchange rate. Readers should understand, therefore, that actual results may be significantly different from forecasts referred to or stated here due to changes in business environments and other factors.